



# 29<sup>th</sup> 태성에스엔이 CAE Conference



## Introduction to Multiscale Analysis and Examples related to PCB

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Hyojun Ha

Taesung S&E

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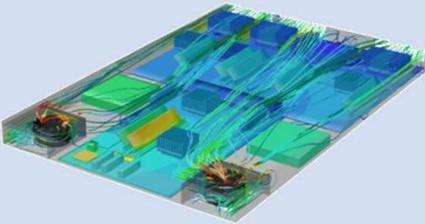
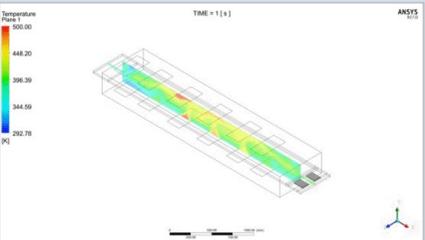
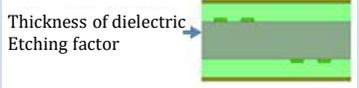
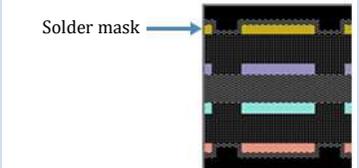
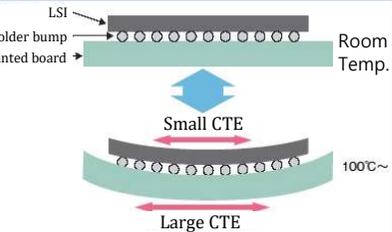
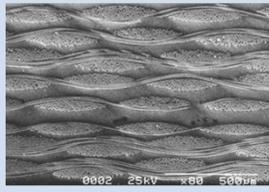
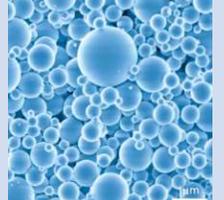


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**Background**

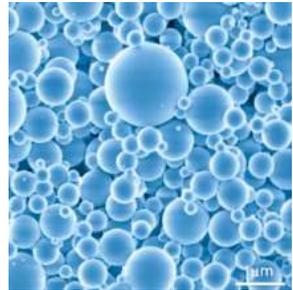
# Occurrence factor of warpage in PCB

Problem	Distributed temperature	Mismatched material constants	Non homogeneous materials
Image	 <p>In operation cooling by fans or fins</p>  <p>In reflow process</p> <p>Heat generation by electronic components</p>	 <p>Thickness of dielectric Etching factor</p>  <p>Solder mask</p>  <p>LSI Solder bump Printed board</p> <p>Room Temp.</p> <p>Small CTE</p> <p>Large CTE</p> <p>100°C~</p>	 <p>Wiring distribution</p>  <p>GFRP (FR4)</p>  <p>Under fill</p>
CAE tools for analysis	ANSYS Fluent ANSYS Icepack ANSYS SI wave	ANSYS Mechanical	Multiscale.Sim(CMAS) ANSYS Mechanical

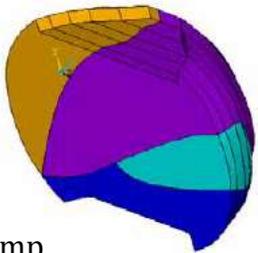
# PCB made by Multi Material

PCB is constructed by many kinds of composite materials

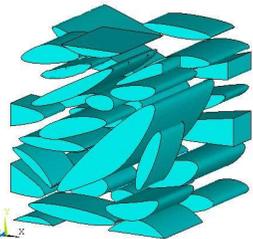
Need an-isotropic material constants for CAE analysis



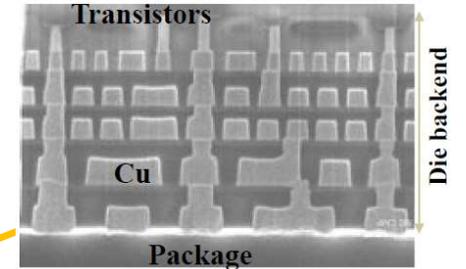
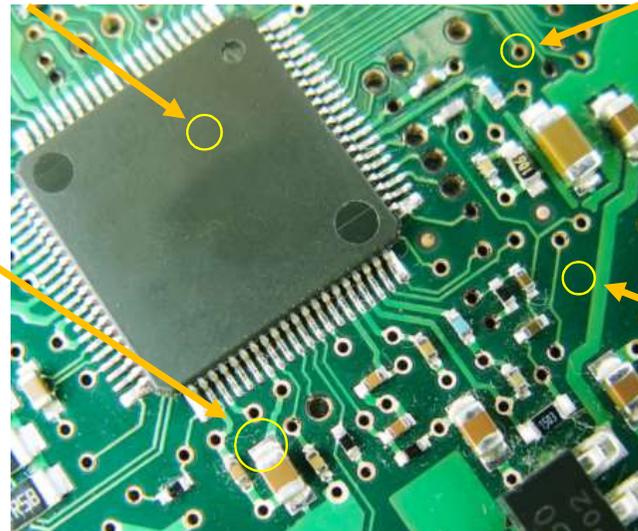
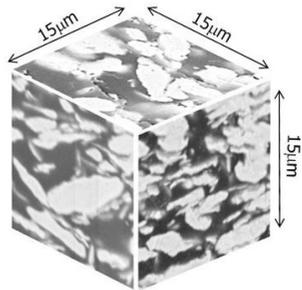
Under fill



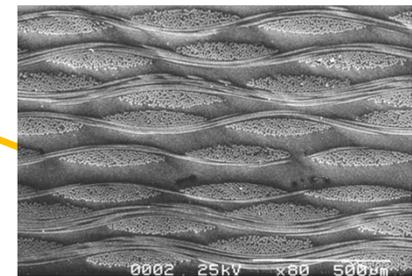
Solder bump



Conductive adhesive(Epoxy & Filler etc.)

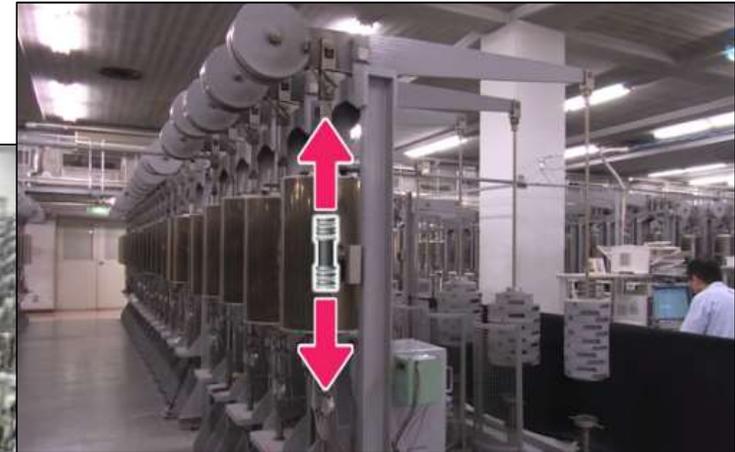


Wiring, Via etc.



Base material (FR4)

Testing just waiting earnestly for a long time



The longest record with respect  
to creep testing  
||  
50 years

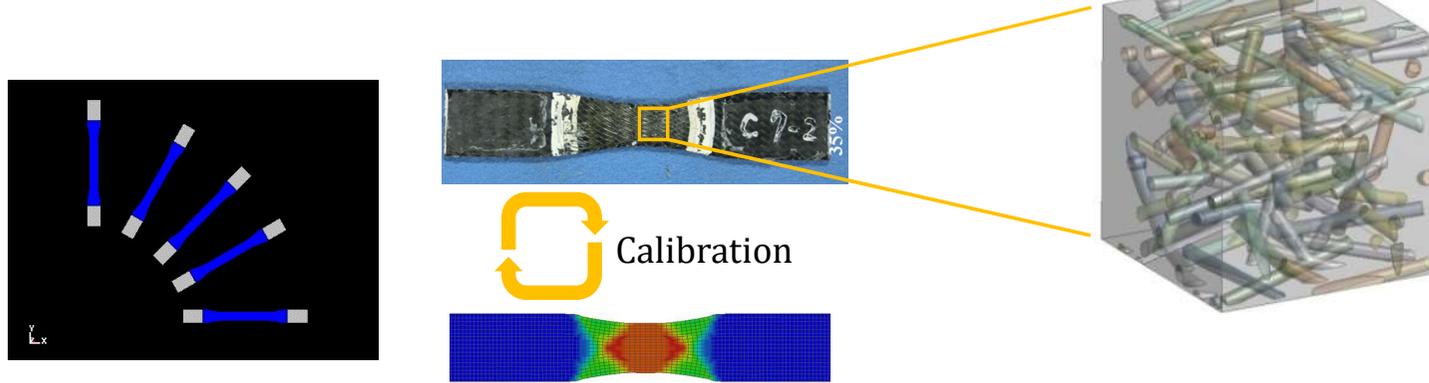
There are 380 testing machines in the  
room which has 15m \* 50m

Reference) National Institute for Materials Science

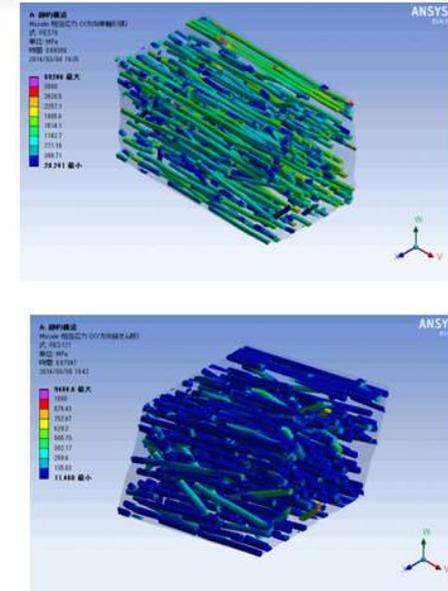
<https://www.nims.go.jp/publicity/digital/movie/mov150916.html>

# Analysis for Material Constants Identification

- Analysis approach to identify material constants
  - Dumbbell specimen model : Reverse identification by calibration
  - Unit cell model : Evaluated definitively from analysis results



Analysis by dumbbell specimen



Analysis by unit cell specimen

Characteristics	Dumbbell specimen	Unit Cell specimen
Cost for model creation	○	△(Tends to get large)
Boundary conditions	○	△(complex)
Consistent with actual tests	○	△
Executable deformation modes	× (limited)	○
Executable identification of all constants	△(limited)	○

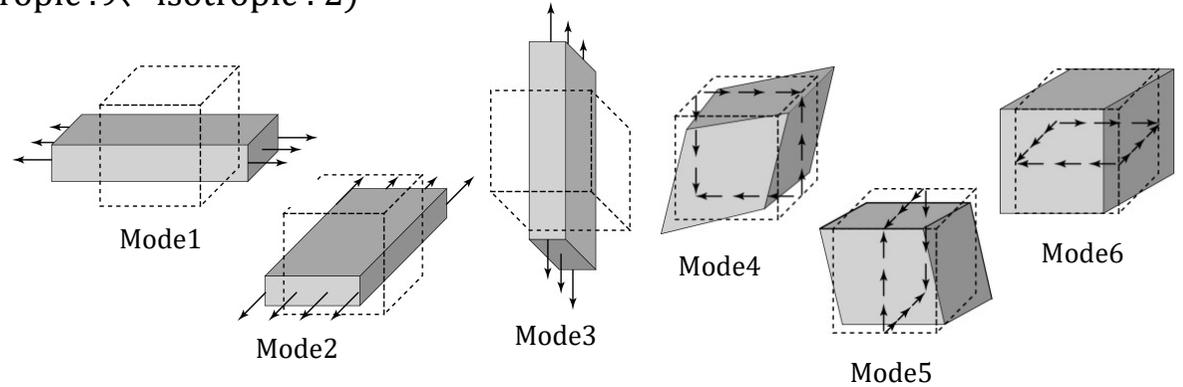
× : bad  
 △ : medium  
 ○ : good

# Material Constants for an isotropic property

## ■ Stiffness matrix for solid

Number of material constant (an isotropic:21, orthotropic:9, isotropic:2)

$$\begin{pmatrix} \sigma_{xx} \\ \sigma_{yy} \\ \sigma_{zz} \\ \tau_{xy} \\ \tau_{yz} \\ \tau_{xz} \end{pmatrix} = \underbrace{\begin{bmatrix} C_{11} & C_{12} & C_{13} & C_{14} & C_{15} & C_{16} \\ C_{21} & C_{22} & C_{23} & C_{24} & C_{25} & C_{26} \\ C_{31} & C_{32} & C_{33} & C_{34} & C_{35} & C_{36} \\ C_{41} & C_{42} & C_{43} & C_{44} & C_{45} & C_{46} \\ C_{51} & C_{52} & C_{53} & C_{54} & C_{55} & C_{56} \\ C_{61} & C_{62} & C_{63} & C_{64} & C_{65} & C_{66} \end{bmatrix}}_{\text{Unknown Parameters}} \begin{pmatrix} \epsilon_{xx} \\ \epsilon_{yy} \\ \epsilon_{zz} \\ \epsilon_{xy} \\ \epsilon_{yz} \\ \epsilon_{xz} \end{pmatrix}$$

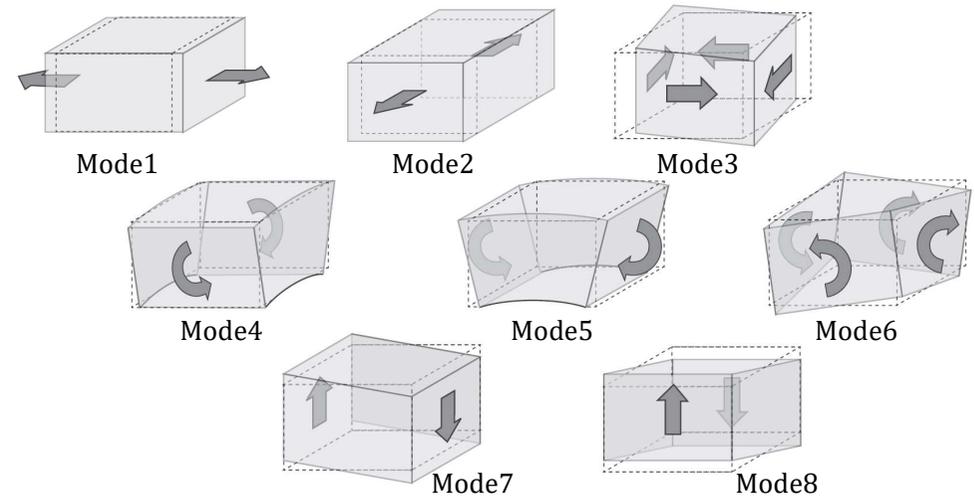


Unknown Parameters

## ■ Stiffness matrix for shell

Number of material constant : 21

$$\begin{pmatrix} N_{11} \\ N_{22} \\ N_{12} \\ M_{11} \\ M_{22} \\ M_{12} \\ S_{23} \\ S_{13} \end{pmatrix} = \underbrace{\begin{bmatrix} A_{11} & A_{12} & A_{13} & B_{11} & B_{21} & B_{31} & 0 & 0 \\ A_{21} & A_{22} & A_{23} & B_{12} & B_{22} & B_{32} & 0 & 0 \\ A_{31} & A_{32} & A_{33} & B_{13} & B_{23} & B_{33} & 0 & 0 \\ B_{11} & B_{12} & B_{13} & D_{11} & D_{12} & D_{13} & 0 & 0 \\ B_{21} & B_{22} & B_{23} & D_{21} & D_{22} & D_{23} & 0 & 0 \\ B_{31} & B_{32} & B_{33} & D_{31} & D_{32} & D_{33} & 0 & 0 \\ 0 & 0 & 0 & 0 & 0 & 0 & E_{11} & E_{12} \\ 0 & 0 & 0 & 0 & 0 & 0 & E_{21} & E_{22} \end{bmatrix}}_{\text{Unknown Parameters}} \begin{pmatrix} e_{11} \\ e_{22} \\ e_{12} \\ \kappa_{11} \\ \kappa_{22} \\ \kappa_{12} \\ g_{23} \\ g_{13} \end{pmatrix}$$



Unknown Parameters

Resultant stress

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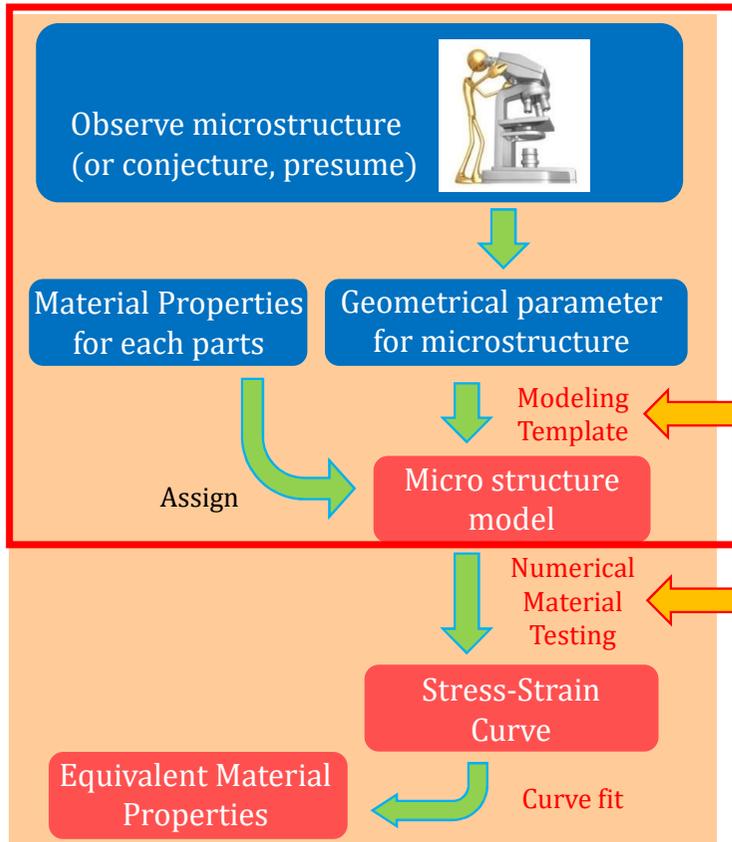
## Introduction of Multiscale Analysis

# Homogenization analysis using Multiscale.Sim



What is Multiscale.Sim?

Add in tool to homogenization analysis on ANSYS Workbench



  : input        : output

Homogenization analysis flow

Model for microstructure

Modeling Template GUI is integrated to Design Modeler

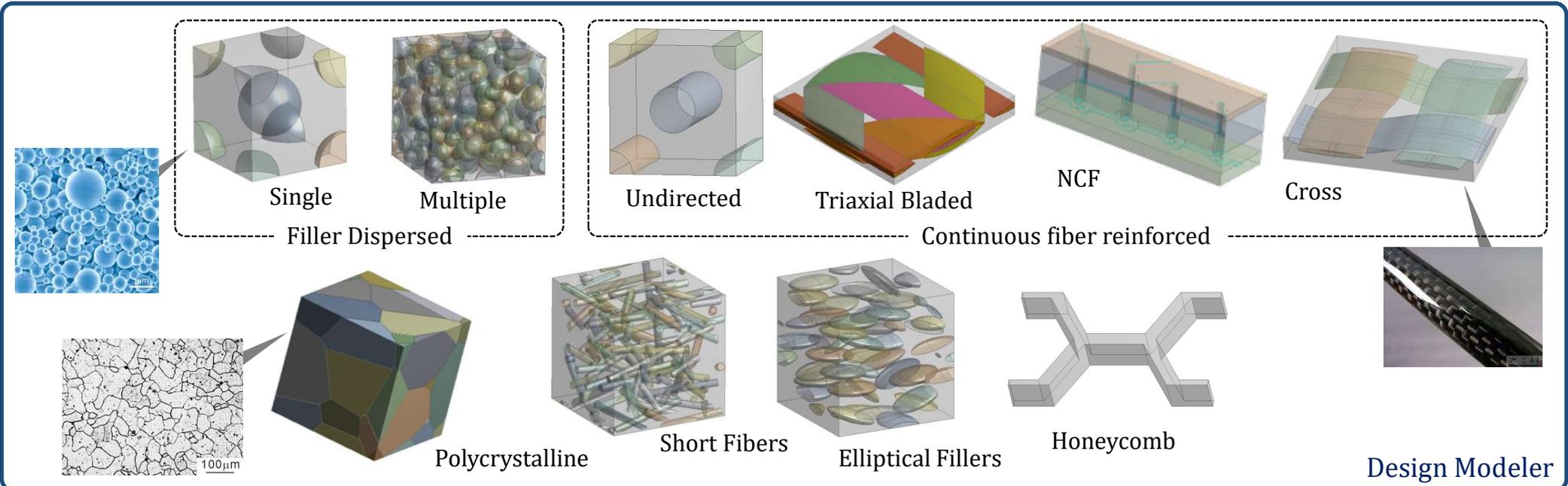
Definition	
<input type="checkbox"/> Unitcell Length X	70 [um]
<input type="checkbox"/> Unitcell Length Y	70 [um]
<input type="checkbox"/> Unitcell Length Z	70 [um]
<input type="checkbox"/> Filler Volume Fraction [%]	20
<input type="checkbox"/> Filler Radius Average	10 [um]
<input type="checkbox"/> Filler Radius Variance	11 [um]
<input type="checkbox"/> Minimum Filler Radius	5 [um]
<input type="checkbox"/> Maximum Filler Radius	20 [um]
<input type="checkbox"/> Filler Gap Tolerance	1 [um]

Uniaxial tension for x dir.      Pure shearing for xy dir.

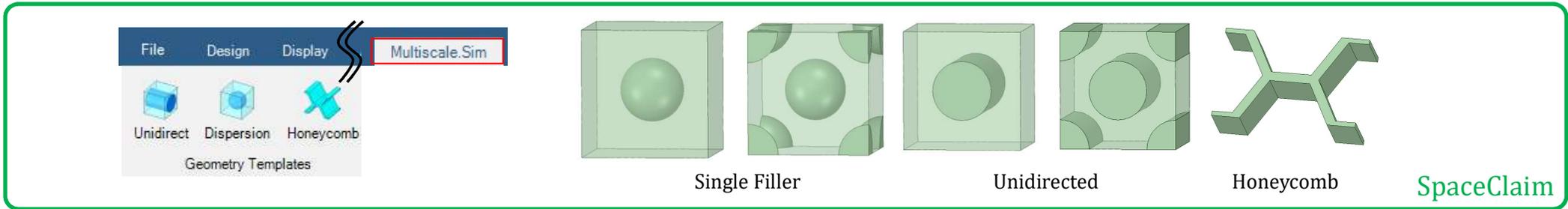
Material test for any deformation mode and loading history

Details of "Material Testing"	
<b>Testing</b>	Material: Elasto-Plastic
Type	Uniaxial
<b>Definition</b>	Uniaxial
Type	Uniaxial support other side load
Testing	Pure shearing
Control	Biaxial
Strain value	Volume
<b>Analysis Set</b>	Components
Stabilization	Program Control

# Templates for Micro Model Creation



Migration



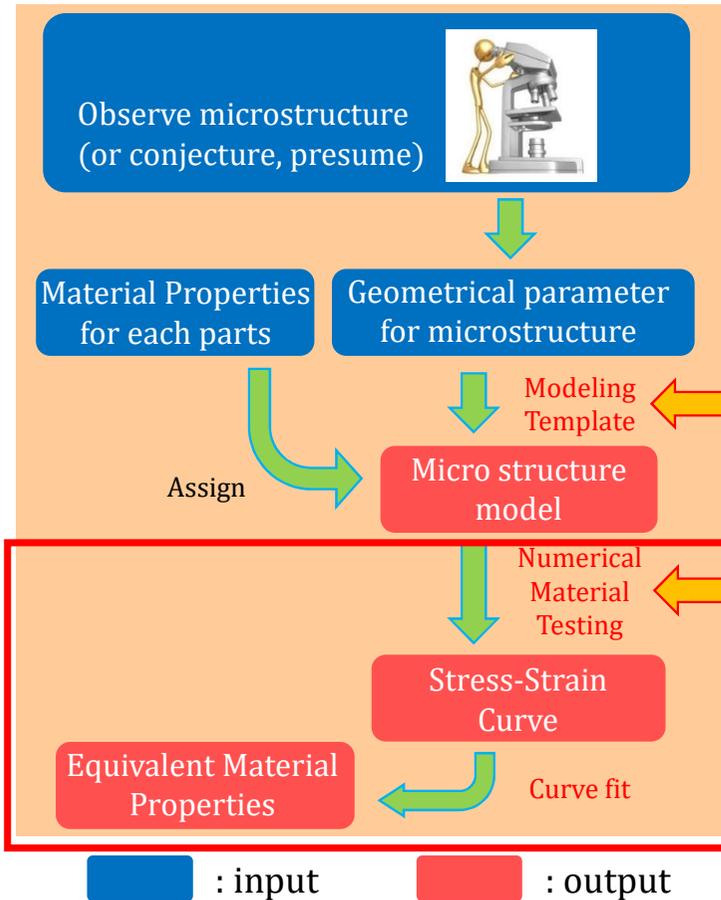
Representative microstructure which can be made by Multiscale.Sim

# Homogenization analysis using Multiscale.Sim



What is Multiscale.Sim?

Add in tool to homogenization analysis on ANSYS Workbench



Homogenization analysis flow

Model for microstructure

Modeling Template GUI is integrated to Design Modeler

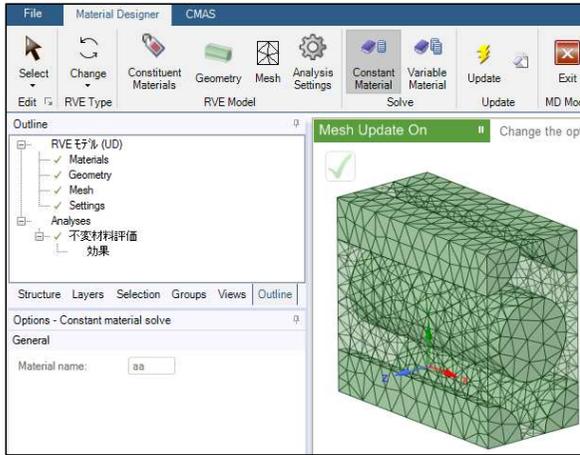
Definition	
Unitcell Length X	70 [um]
Unitcell Length Y	70 [um]
Unitcell Length Z	70 [um]
Filler Volume Fraction [%]	20
Filler Radius Average	10 [um]
Filler Radius Variance	11 [um]
Minimum Filler Radius	5 [um]
Maximum Filler Radius	20 [um]
Filler Gap Tolerance	1 [um]

Uniaxial tension for x dir.      Pure shearing for xy dir.

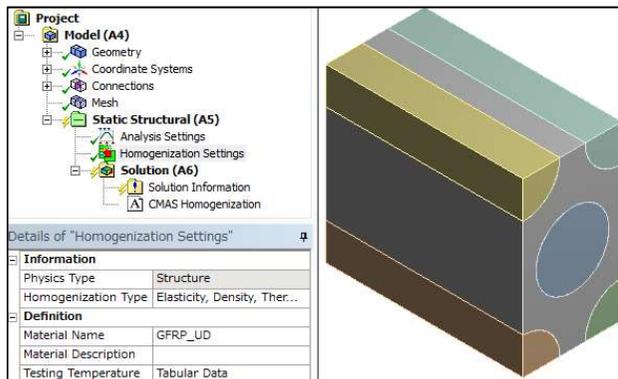
Material test for any deformation mode and loading history

Details of "Material Testing"	
<b>Testing</b>	Elasto-Plastic
Type	Uniaxial
<b>Definition</b>	Uniaxial
Type	Uniaxial support other side load
Testing	Pure shearing
Control	Biaxial
Strain value	Volume
<b>Analysis Set</b>	Components
Stabilization	Program Control

# Material Designer vs. Multiscale.Sim



Material Designer released from 2019  
(SpaceClaim GUI)



Multiscale.Sim released from 2007  
(Mechanical GUI)

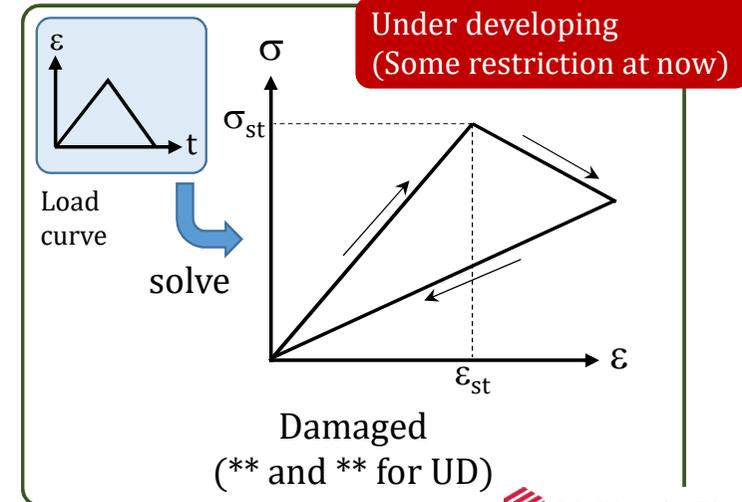
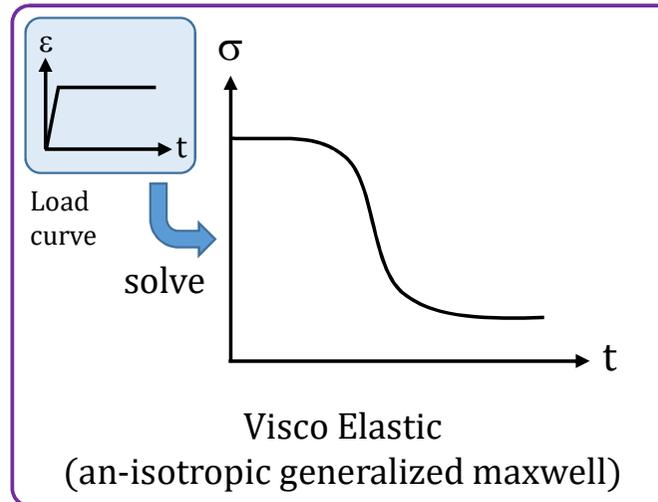
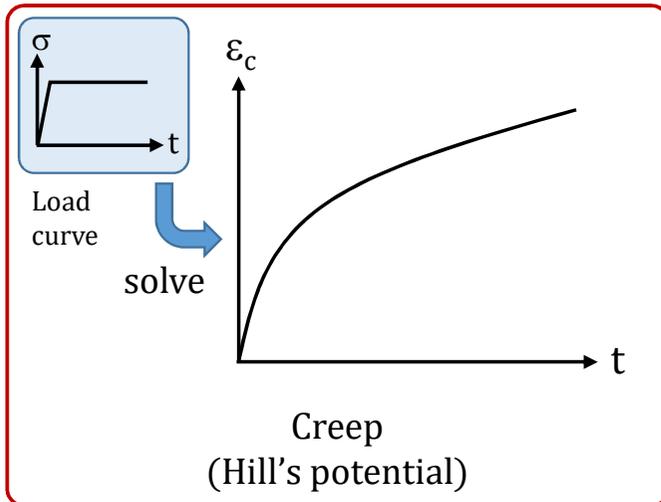
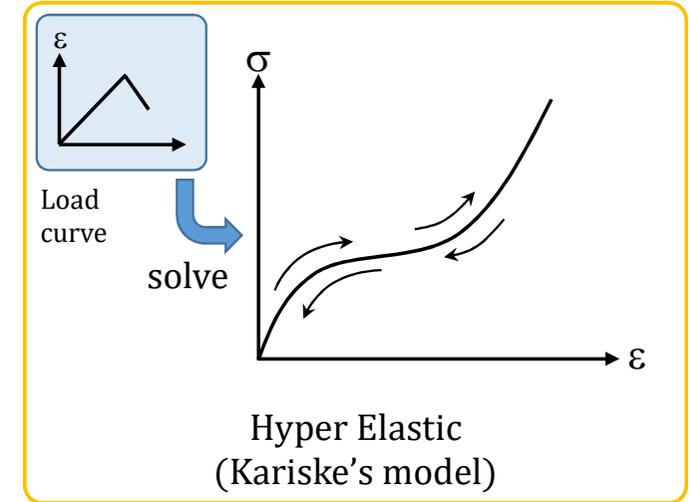
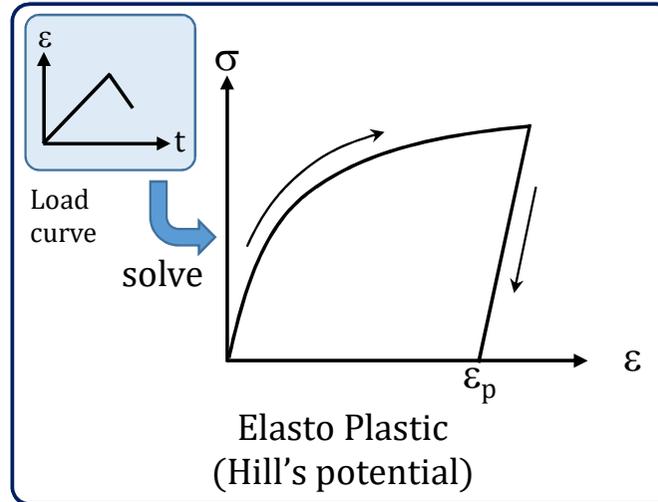
Homogenization analysis tool is made by broadly two features which are model creation and homogenization analysis.

Feature comparison between two tools (as of Aug. 28, 2019)

Features		Material Designer	Multiscale.Sim
GUI		SpaceClaim	Mechanical
Micro model creation		5 types	17 types (Design Modeler)
License to use		ANSYS Mechanical Enterprise	Multiscale.Sim
Linear Homogenization	Elasticity	✓	✓
	Thermal expans.	✓	✓
	Integrated section		✓
	Thermal conduct.	✓	✓
	Seepage coeff.		✓
	Permeability for Electric and Magnetic		✓
Nonlinear Homogenization	Next slides for detail		✓
Localization			✓

## Nonlinear homogenization features

- Numerical Material testing
  - Any deformation mode
  - Any loading history
- Curve fitting
  - Original optimization algorithm (Tuned for each material models)



## ■ Purpose

Identification equivalent material constants for

- Orthotropic elasticity
- Coefficient of thermal expansion
- Density

## ■ Analysis Model

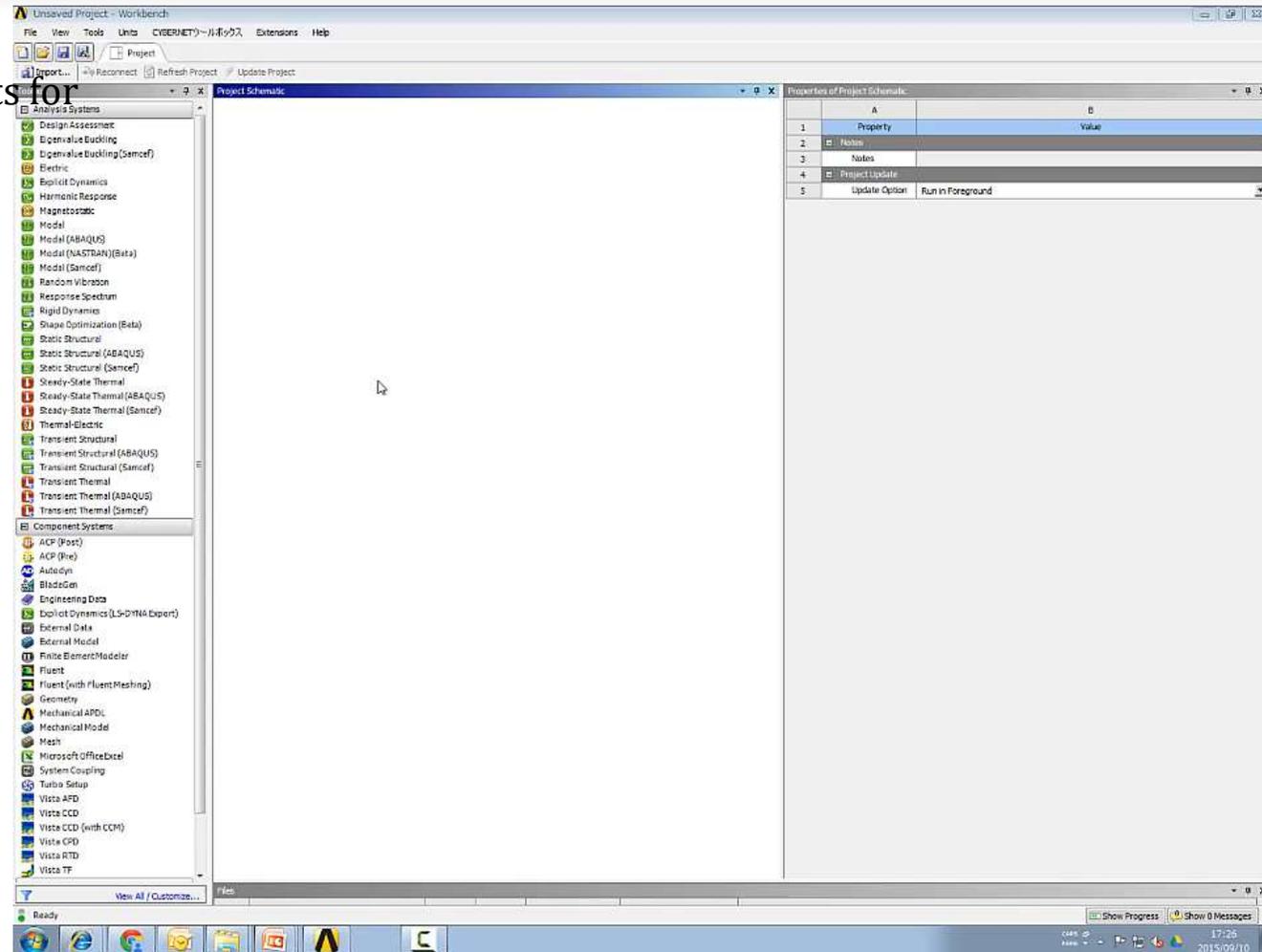
- SiC matrix & Aluminum filler
- Spherical filler dispersed in SiC

## ■ Material Type

- SiC : Pure Elastic
- Aluminum : Pure Elastic

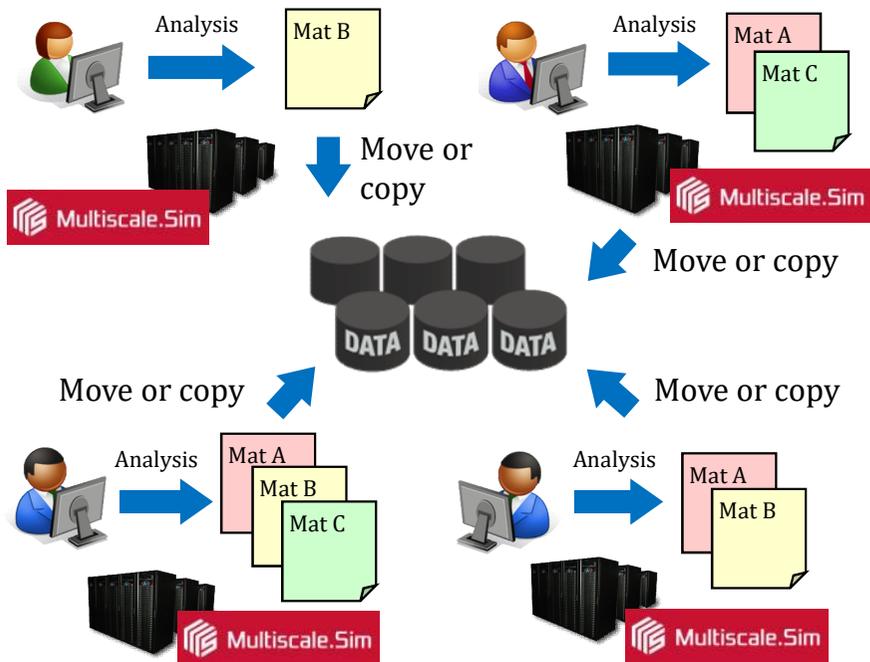
## ■ Operational Procedure

- Create Analysis System
- Creating microstructure
- Assigning material properties & Meshing
- Insert linear homogenization objects
- Confirmation results



Homogenization analysis in SPDM system  
(SPDM : Simulation Process and Data Management)

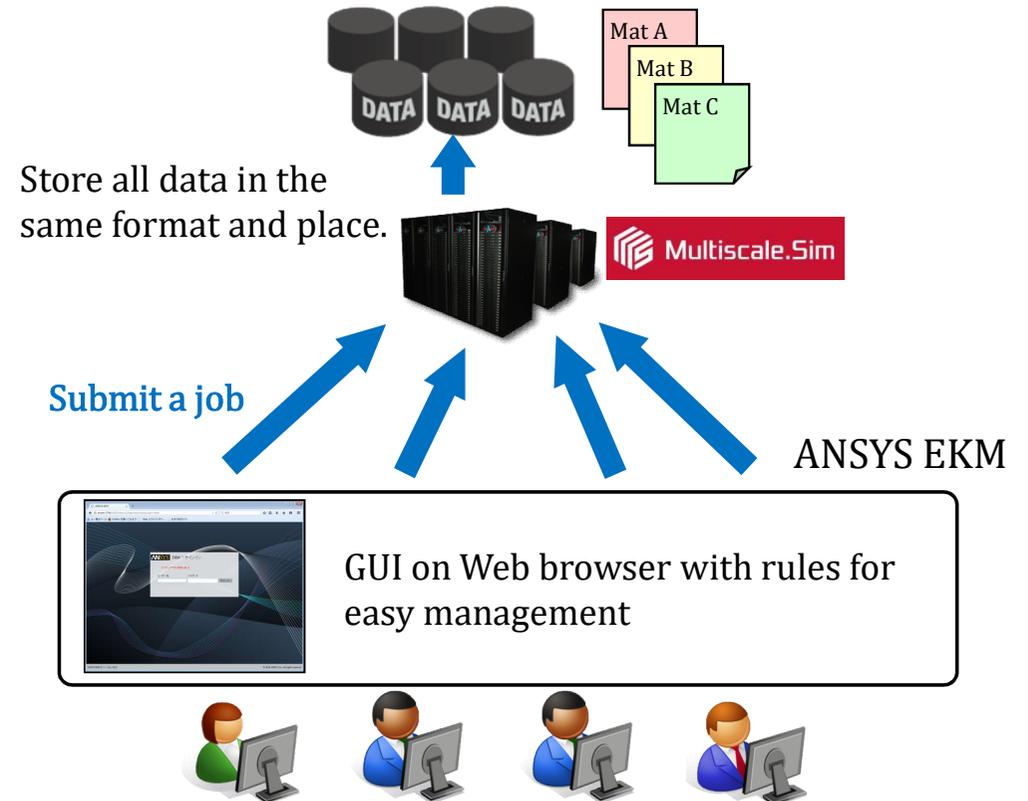
## Conventional process



### Demerit

- Duplication of data
- Lack of unity (spelling inconsistency)
- Different information although same name
- Unknown source

## SPDM process

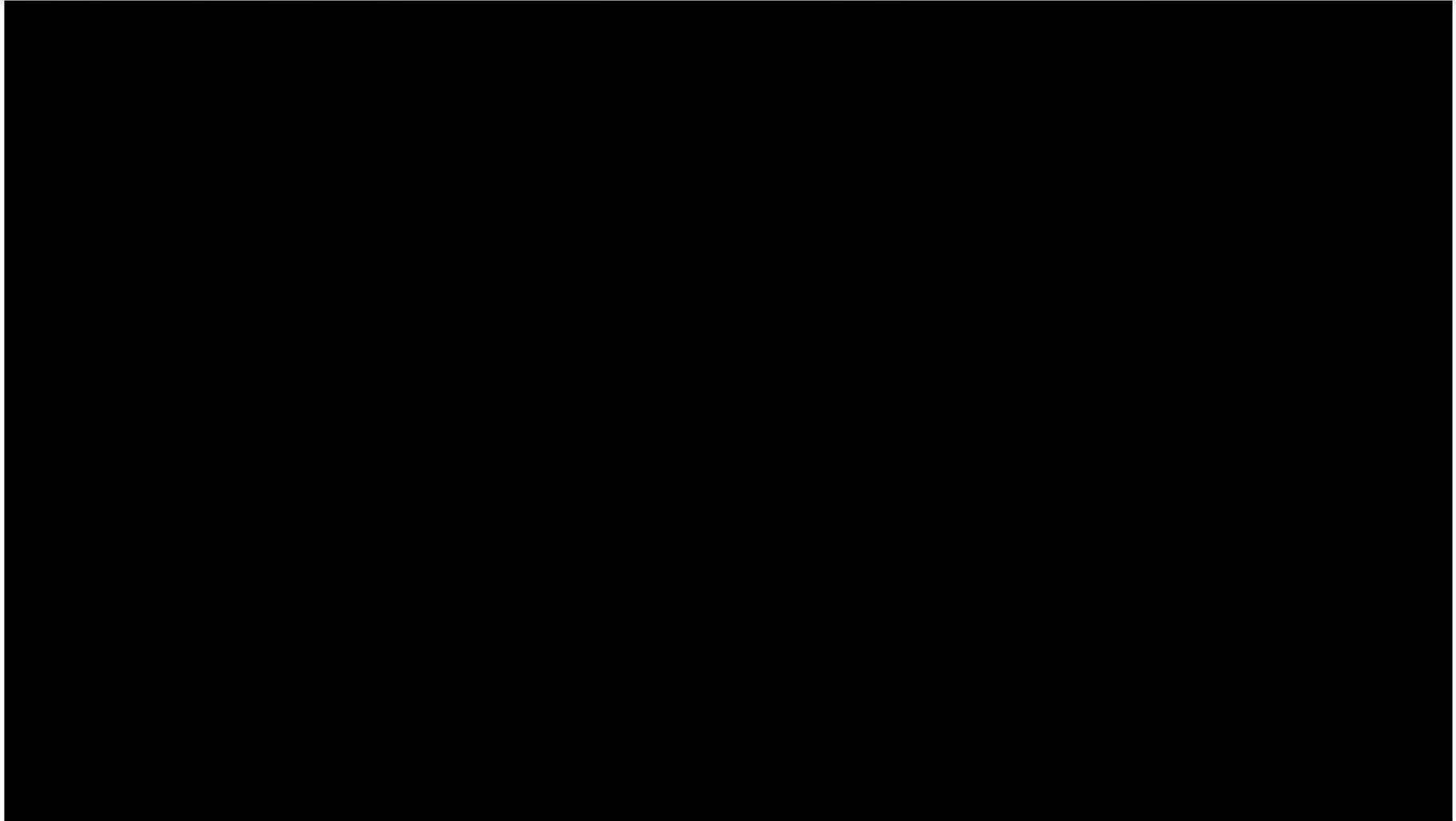


Store all data in the same format and place.

Submit a job

ANSYS EKM

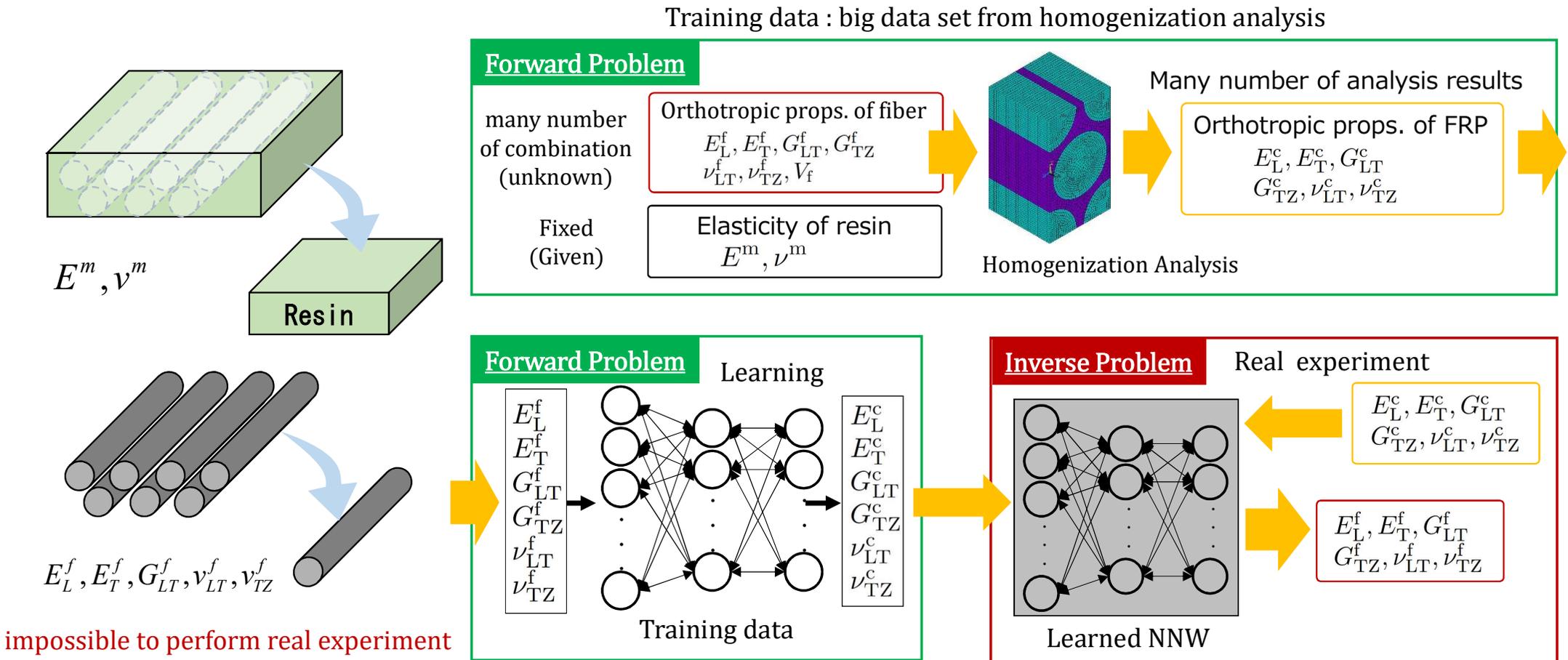
GUI on Web browser with rules for easy management



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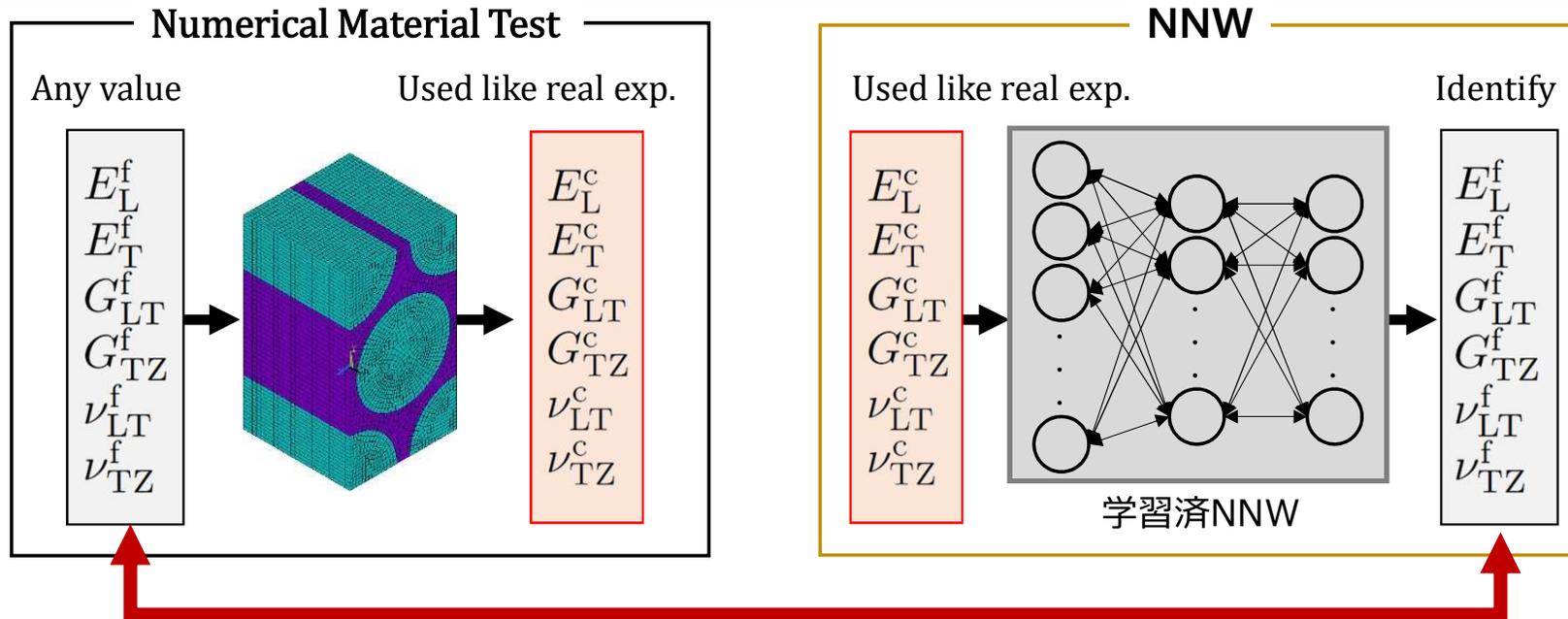
## Analysis Examples

# How to prepare material constants for input data



Reference) S. Tsuchida, N. Hirayama, Y. Ishibashi, K. Yamamoto, K. Terada, Identification of orthotropic elastic constants for carbon fiber, Composite Symposium in Japan (2018)

# How to prepare material constants for input data



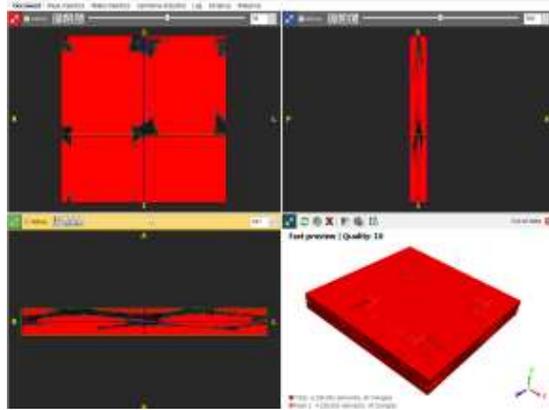
Props.	Unit	Data	NNW	Error rate [%]
$E_L^f$	GPa	237.5	239.1	0.67
$E_T^f$	GPa	16.5	16.90	2.30
$G_{LT}^f$	GPa	9.5	9.40	1.05
$\nu_{LT}^f$	-	0.33	0.33	0.00
$\nu_{TZ}^f$	-	0.50	0.51	2.00

Reference) S. Tsuchida, N. Hirayama, Y. Ishibashi, K. Yamamoto, K. Terada, Identification of orthotropic elastic constants for carbon fiber, Composite Symposium in Japan (2018)

# Elasticity homogenization for woven CFRP

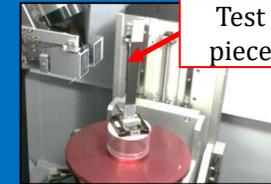
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Image analysis for identification of geometrical parameters



Simplware®

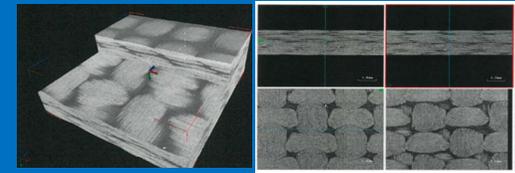
Image info. by DICOM data



Test piece



inspeXio SMX-225CT FPD HR from Shimadzu corp.

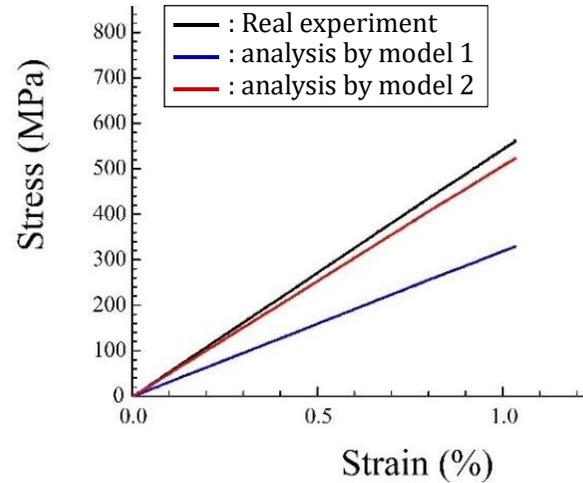


Micro focus X-ray CT system

Model 1

Model 2

- Model 1
  - Modeled woven shape by sine curve function
  - Volume fraction is not accurate
- Model 2
  - Modeled based on geometrical parameter as a result of X-ray observation



Validation

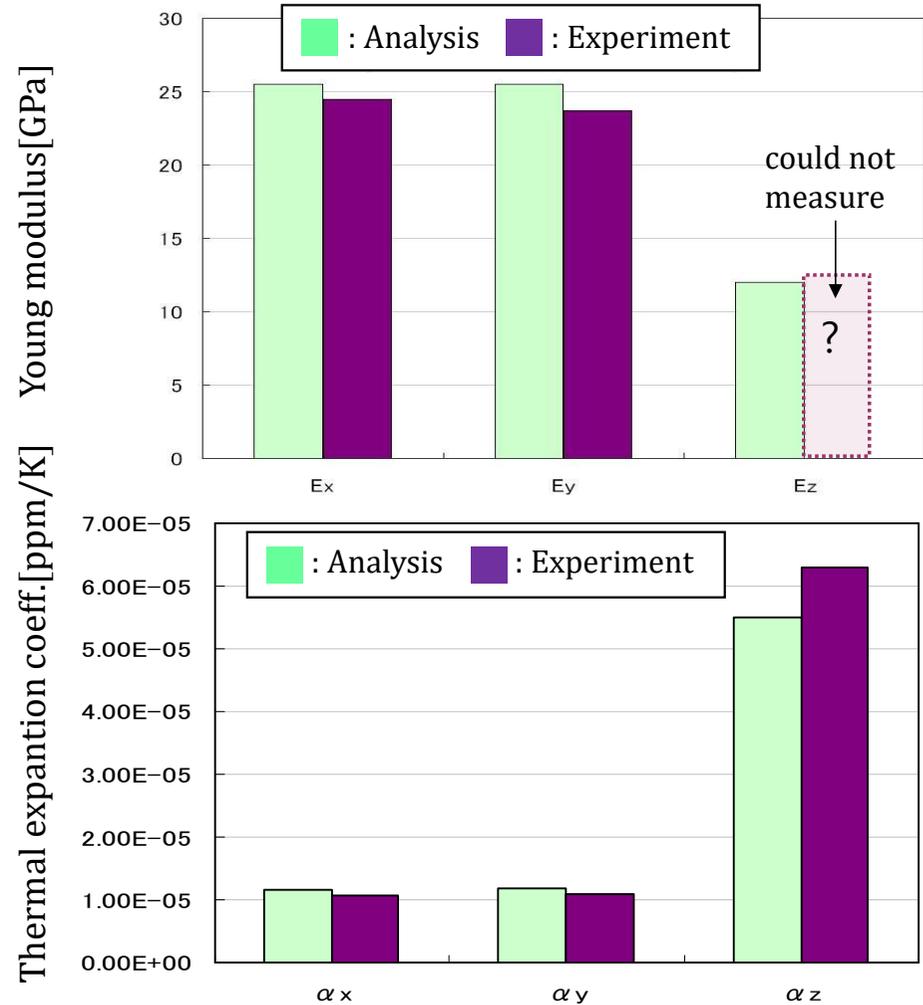
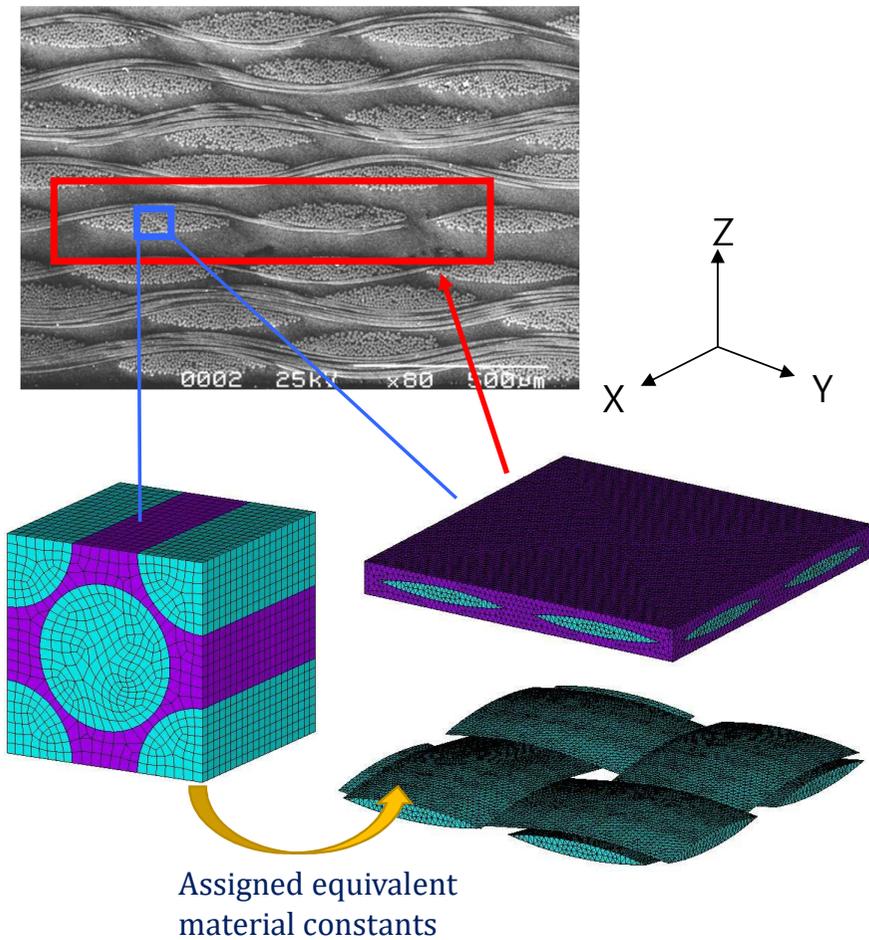
Autograph

Precision universal tester

\* Courtesy of Shimadzu corporation

# FR4 (Glass fiber and Epoxy)

- Grass cross used PCB and so on
- Evaluate elasticity and thermal expansion



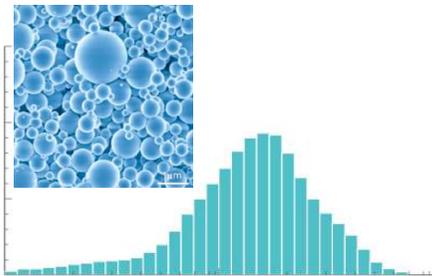
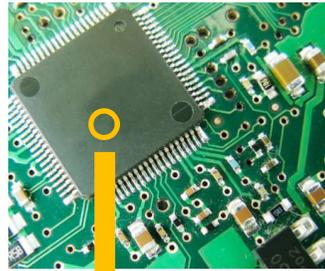
Courtesy of NITTO BOSEKI Co., Ltd.

# Filler dispersed composite

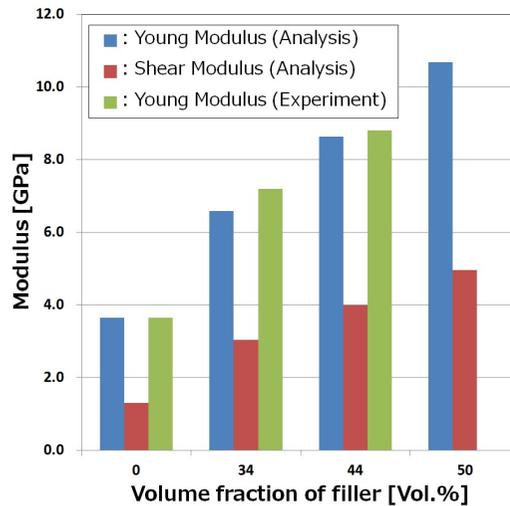
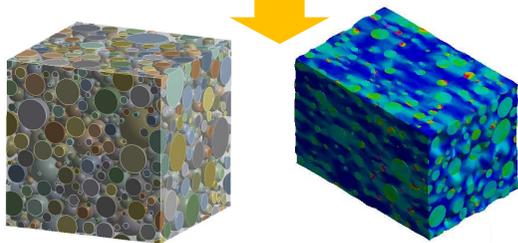
## ■ Sealing resin

Material property is controlled by fillers

- Model
  - SiC filler + Epoxy resin
  - Spherical filler
  - Consider size distribution
- Homogenization
  - Elastic



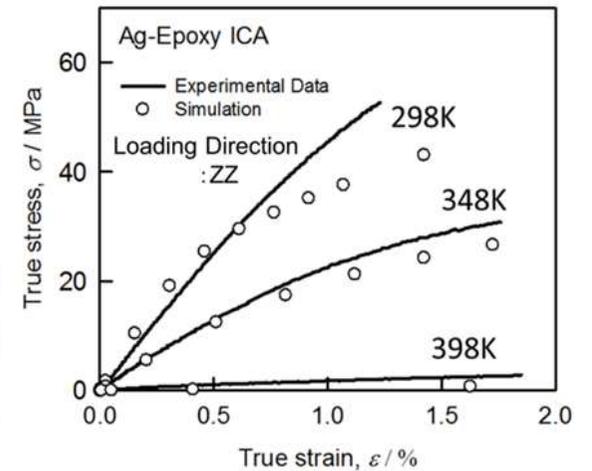
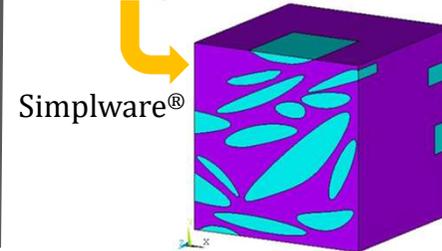
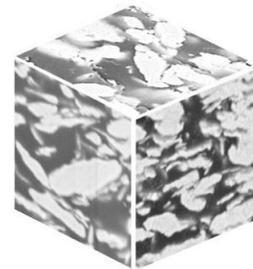
Size distribution



## ■ Conductive adhesive

Add Ag filler in matrix in order to achieve high conductivity

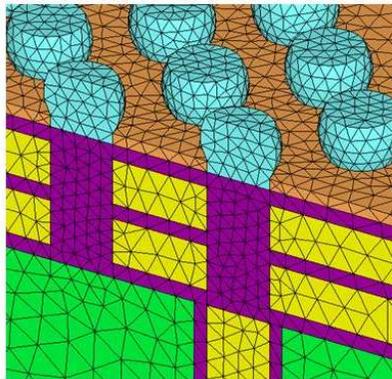
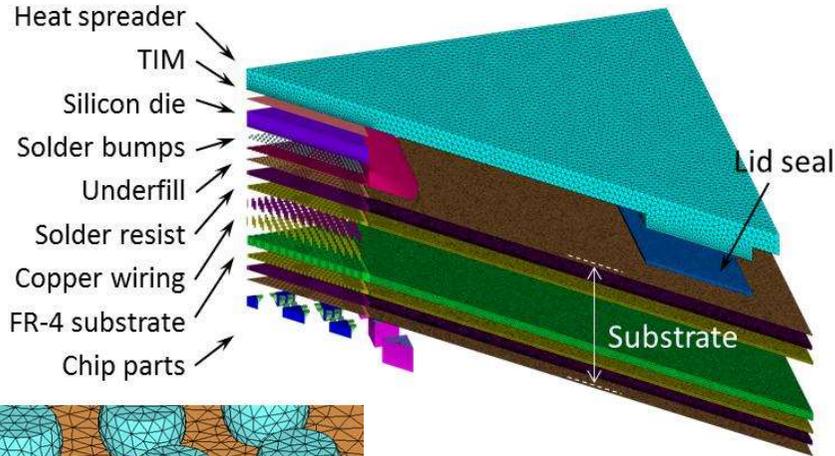
- Modeling
  - Ag filler + Epoxy resin
  - Complex filler's shape
  - Create by image base technique (Delete small parts)
- Homogenization
  - Elasto Plastic



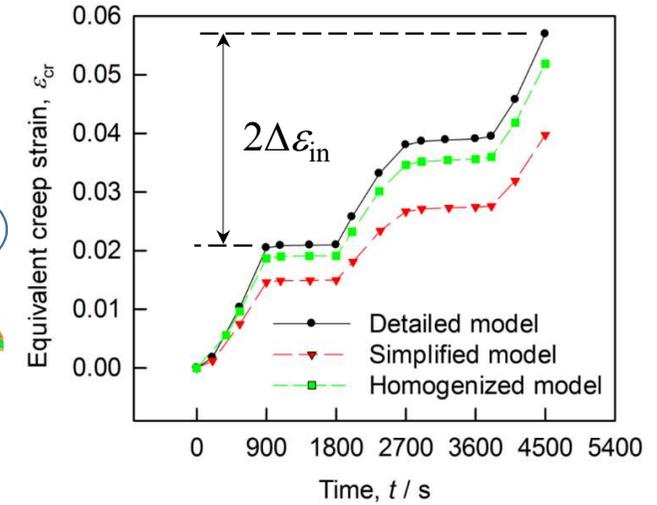
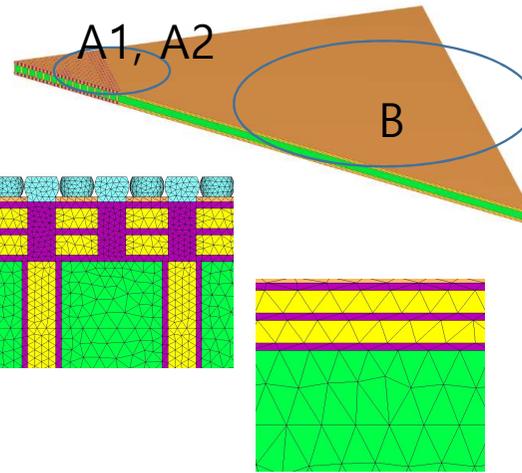
# Semiconductor Package

➤ Model  
Considering Cu wiring structure under the bump.

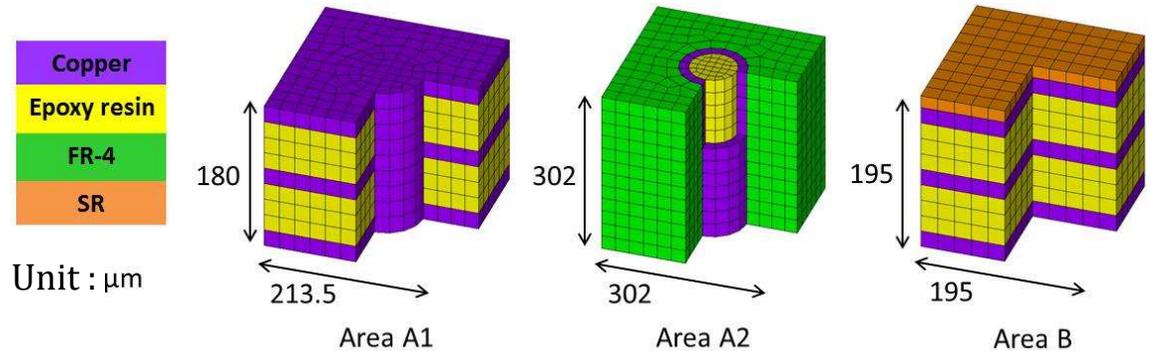
➤ Purpose  
Analyze the effect of wiring structure on the strain in bump.



(About Ten million nodes)



Estimate anisotropic material constants at three point and replace homogenized model.



PCB is multi material product made by many composite.  
It is important to prepare it's an-isotropic material constants.

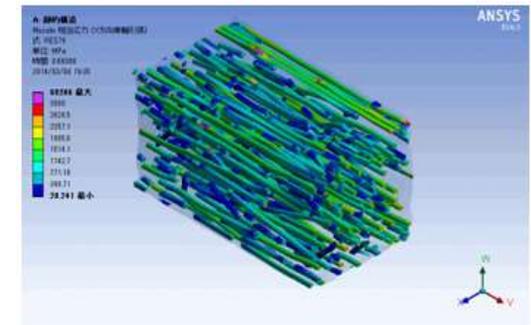
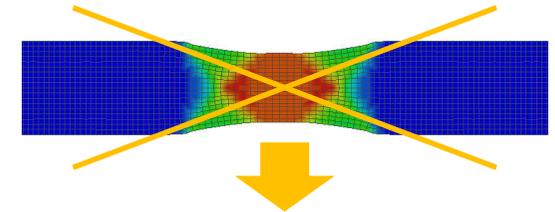
Multiscale analysis approach based on homogenization technique is quite effective.

### Difficulties of real experiments

Making all deformation modes for identification of an-isotropic properties  
Taking a long time to perform.

### Homogenization analysis solution

- Micro Model Creation
  - Many templates to create model automatically
- Numerical Material Test
  - Available for any deformation modes and loading history
- Curve fitting
  - Robust optimization algorithm to identify material constants



Good Material Database Leads Good Analysis



29<sup>th</sup> 태성에스엔이  
**CAE**  
**Conference**

**Backup Slides**

# Simple examples for creep homogenization

## Multiscale creep analysis for lattice structure

### Creep homogenization analysis

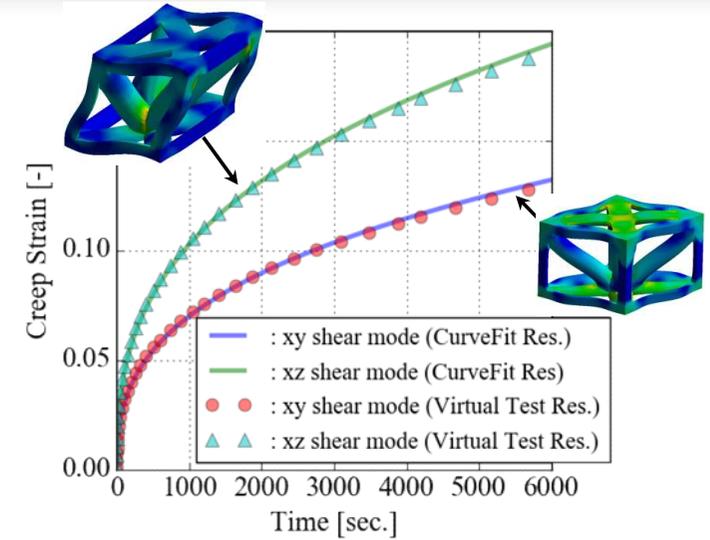
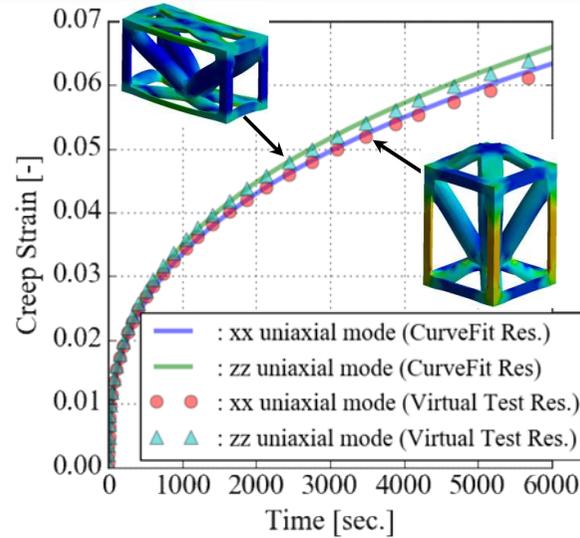
- Virtual test for 6 modes
  - xx,yy,zz uniaxial modes
  - xy,yz,xz pure shearing modes
- Curve fitting
  - PSO optimization
- Macroscopic constitutive law
  - Time hardening & Hill's potential

$$\dot{\epsilon}_{cr} = C_1 \sigma_{Hill}^{C_2} t^{C_3} \exp\left(-\frac{C_4}{T}\right)$$

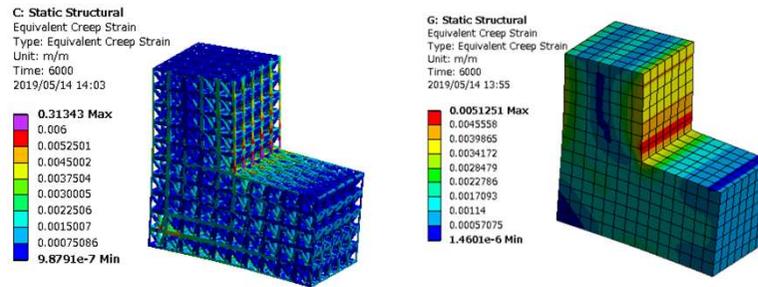
$$\sigma_{Hill} = \left\{ F(\sigma_{yy} - \sigma_{zz})^2 + G(\sigma_{zz} - \sigma_{xx})^2 + H(\sigma_{xx} - \sigma_{yy})^2 + 2N\tau_{xy}^2 + 2L\tau_{yz}^2 + 2M\tau_{xz}^2 \right\}^{1/2}$$

### Macro scale analysis

- Direct model is used for validation
- Good correlation between 2 model.



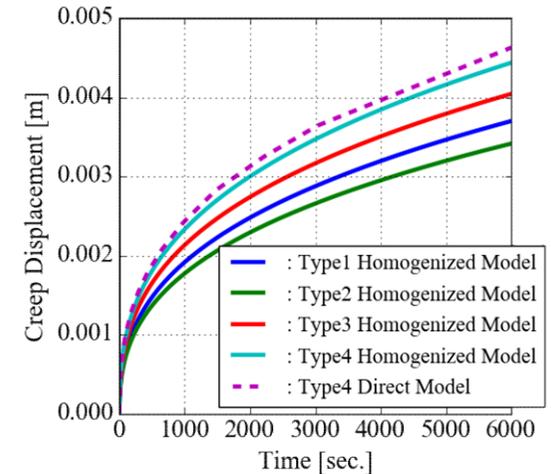
Creep behavior obtained virtual testing and the result of curve fitting



Direct Model  
(Comput. Time=155 hours)

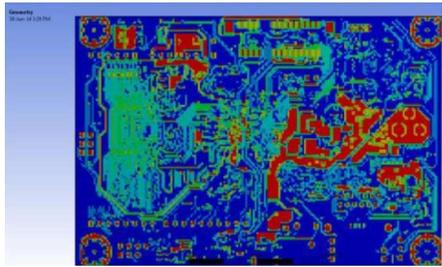
Homogenized Model  
(Comput. Time=4 min)

**Faster 2300 times**

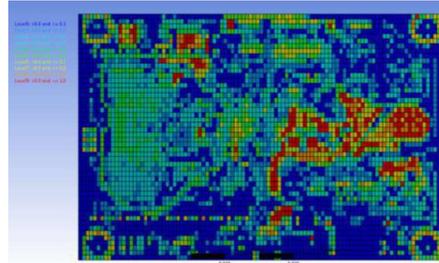




## Trace Mapping



ECAD data



ECAD

### ➤ Mixing rule

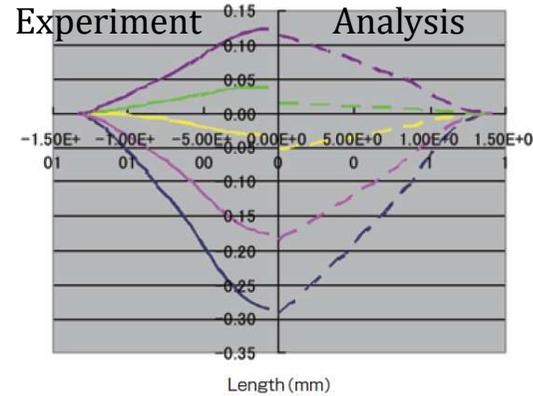
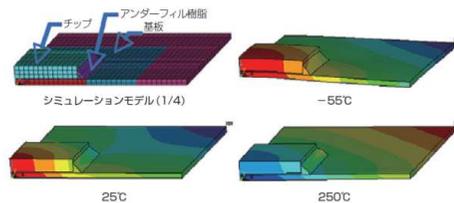
$$E_x^{\text{eff}}, E_y^{\text{eff}} = \frac{1}{\frac{f_s}{E_s} + \frac{f_u}{E_u} - \frac{f_s f_u (\nu_s E_u - \nu_u E_s)^2}{E_s E_u (f_s E_s - f_u E_u)}}$$

$$E_z^{\text{eff}} = f_s E_s + f_u E_u \quad \nu^{\text{eff}} = f_s \nu_s + f_u \nu_u$$

$$\alpha_z^{\text{eff}} = \frac{f_s E_s \alpha_s + f_u E_u \alpha_u}{f_s E_s + f_u E_u}$$

$$\alpha_x^{\text{eff}}, \alpha_y^{\text{eff}} = (1 + \nu_u) + \alpha_u f_u + (1 + \nu_s) \alpha_s f_s - \alpha_z^{\text{eff}} \nu^{\text{eff}}$$

- Material property
  - Board : homogenized anisotropic CTE at 9 regions
  - UF : visco elastic property of UF
- Real experiment
  - DIC technique



— 250°C — 175°C — 125°C — 25°C — -55°C  
 - - 250°C - - 175°C - - 125°C - - 25°C - - -55°C

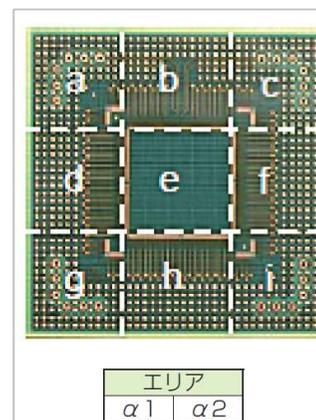
【Package on Package】

20mm  
20mm  
20mm  
FCA側 BGA側

276µm  
TOTAL Thickness 276µm

デザインルール  
 チップサイズ 7.3mm×7.3mm  
 基板サイズ 20mm×20mm 単位: µm

最小ライン幅	30
最小ライン幅-ライン間スペース	50
PoP & BGA	ピッチ パッド径 はんだ保護膜開口サイズ 250dia.
FCA	最小ピッチ パッドサイズ はんだ保護膜開口サイズ パッド数 80 40×110 300 328



エリア  
α1 α2

X direction (ppm/°C)

a	b	c
18.7	14.8	15.4
13.2	15.3	17.6
17.2	12.4	17.6
11.6	14.8	12.8

Y direction (ppm/°C)

a	b	c
18.5	12.8	16.0
11.2	16.1	11.2
17.8	12.8	16.6
18.8	16.8	14.8
17.0	12.0	17.2
13.2	15.4	20.4